

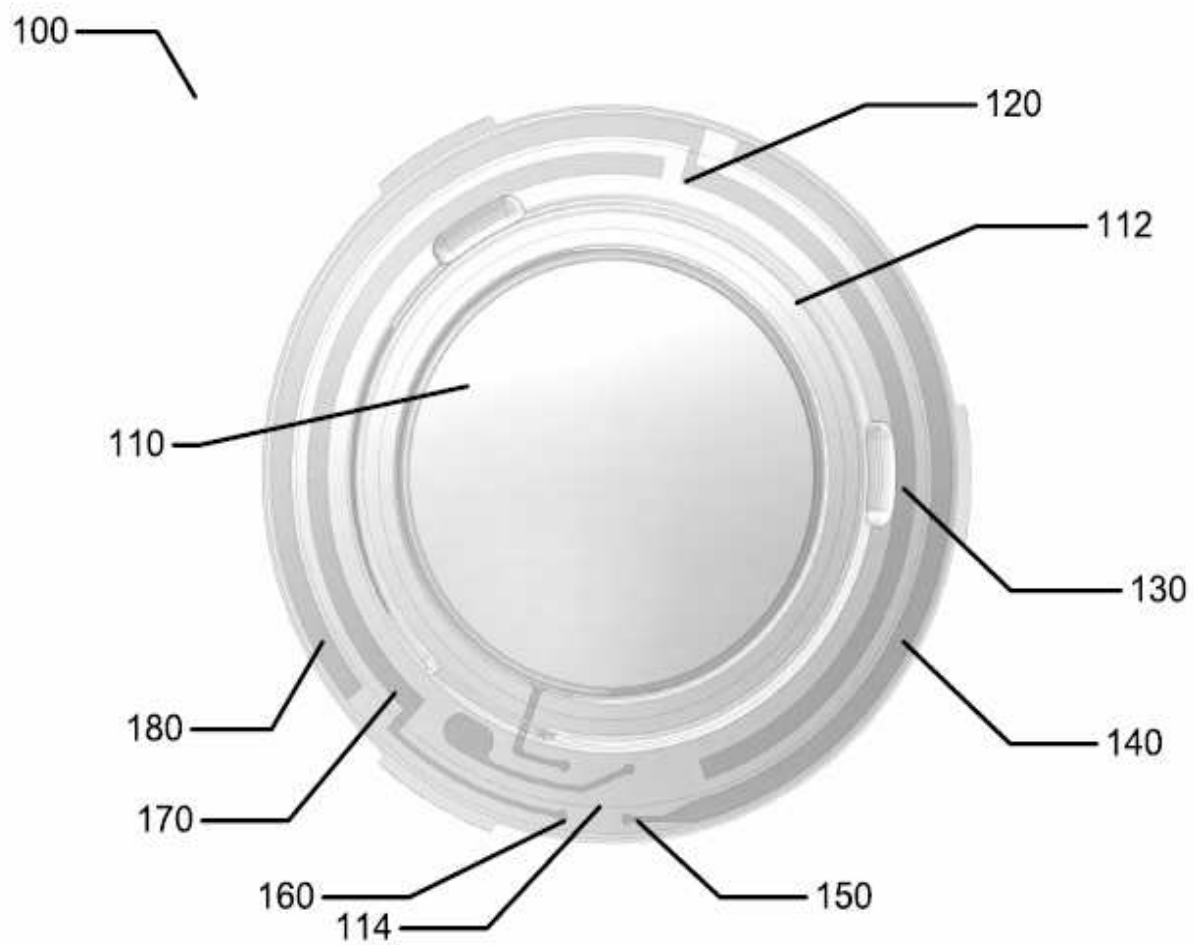


FIG. 1

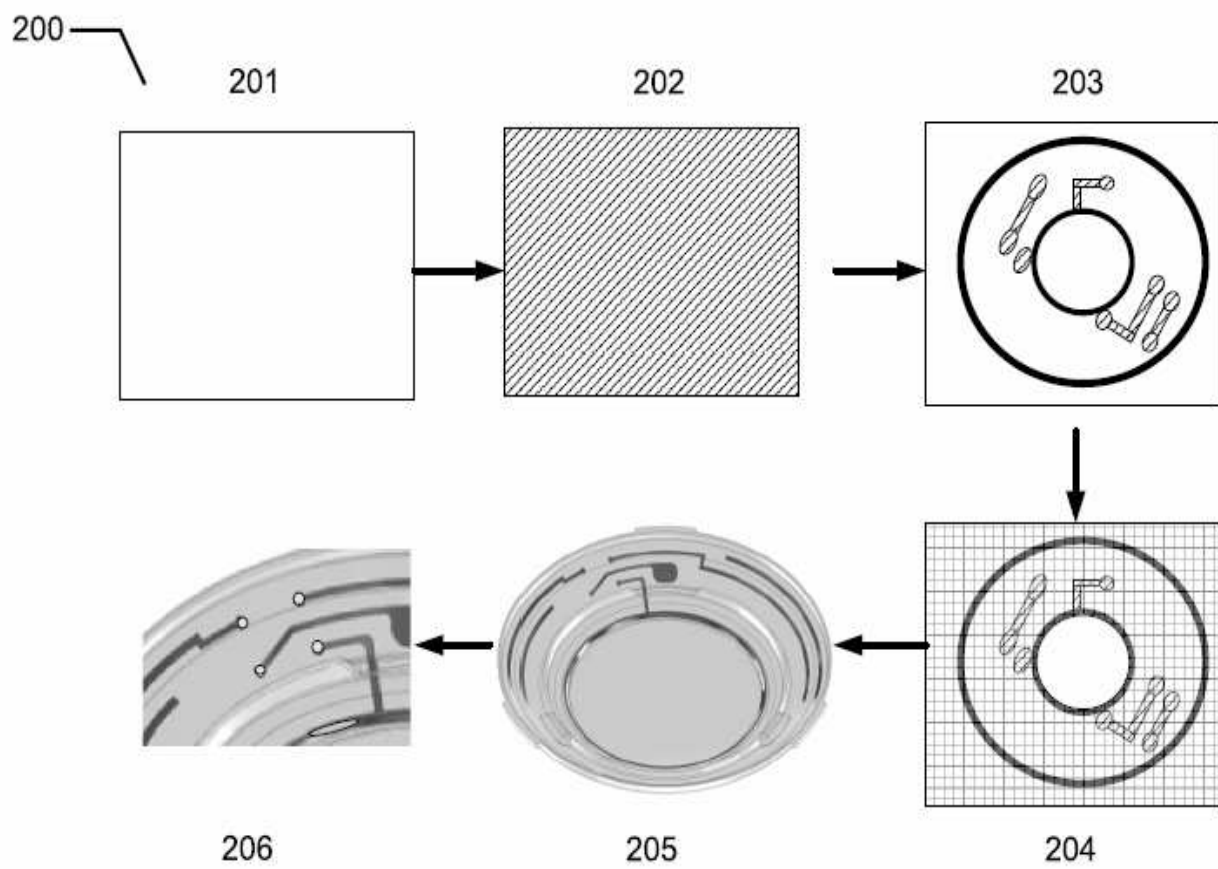


FIG. 2

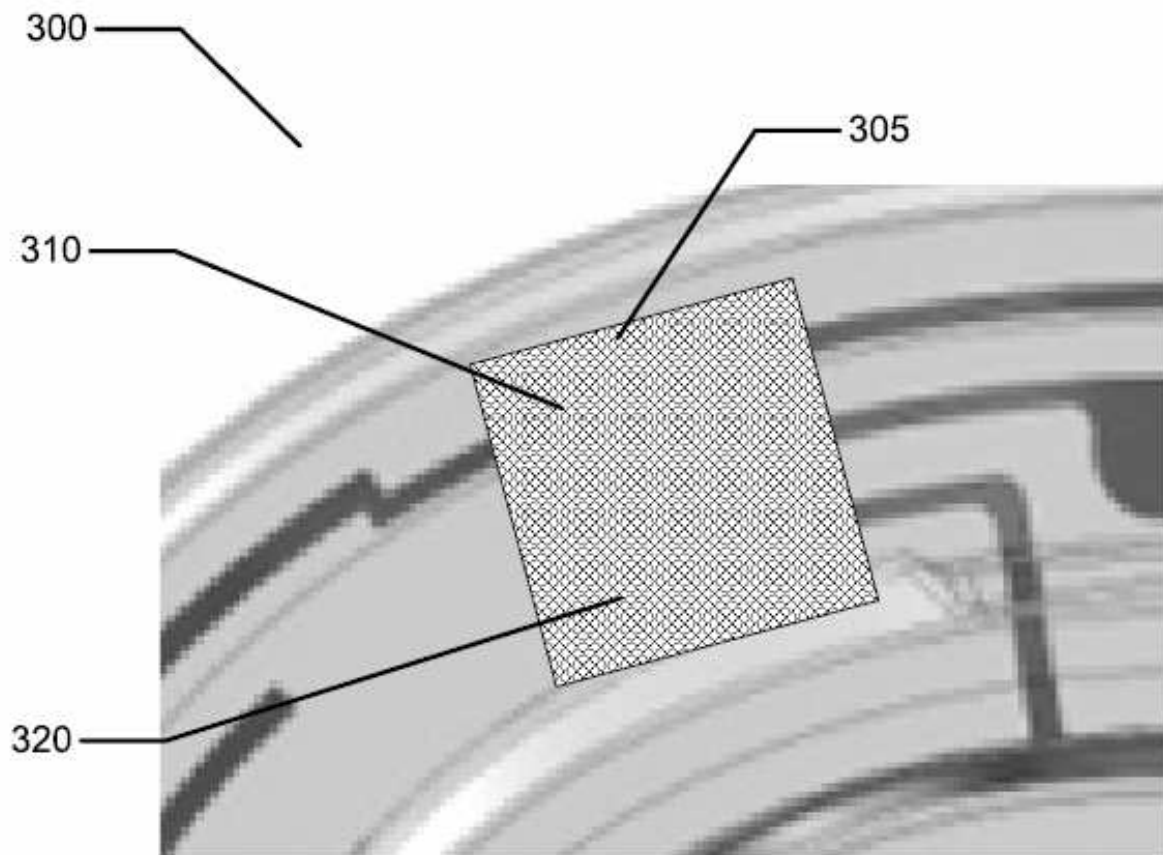


FIG. 3

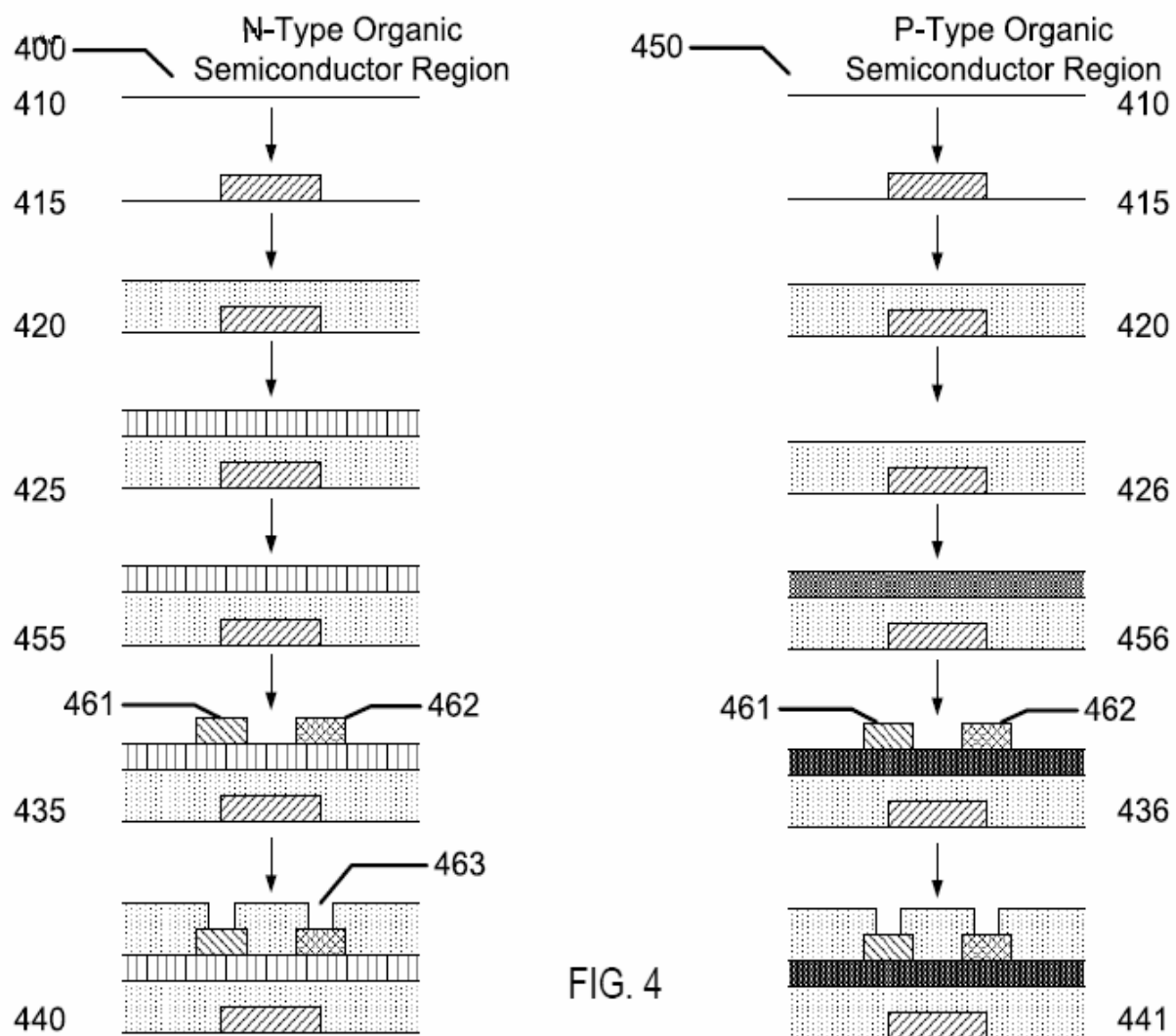


FIG. 4

500

CLEAN THE SURFACE OF A FLAT SUBSTRATE	501
DEPOSIT GATE METAL FEATURES	502
DEPOSIT DIELECTRIC FILM LAYER	503
DEPOSIT p-TYPE ORGANIC SEMICONDUCTOR LAYER IN SELECTED REGIONS	504
DEPOSIT n-TYPE ORGANIC SEMICONDUCTOR LAYER IN SELECTED REGIONS	505
DEPOSIT SOURCE AND DRAIN METALLIC ELECTRODES	506
DEPOSIT DIELECTRIC INSULATING LAYER	507
OPEN CONTACT "HOLES" INTO DIELECTRIC INSULATING LAYERS AT LEAST PARTIALLY ABOVE METALLIC ELECTRODES	508

FIG. 5

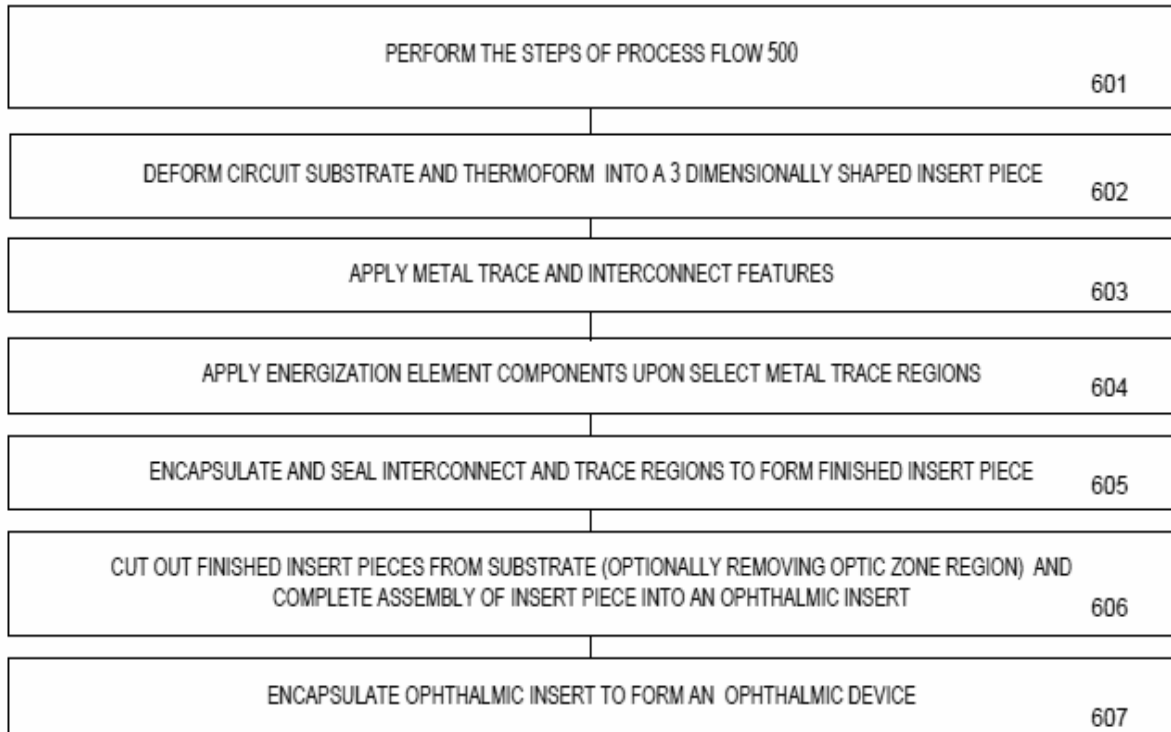
600

FIG. 6

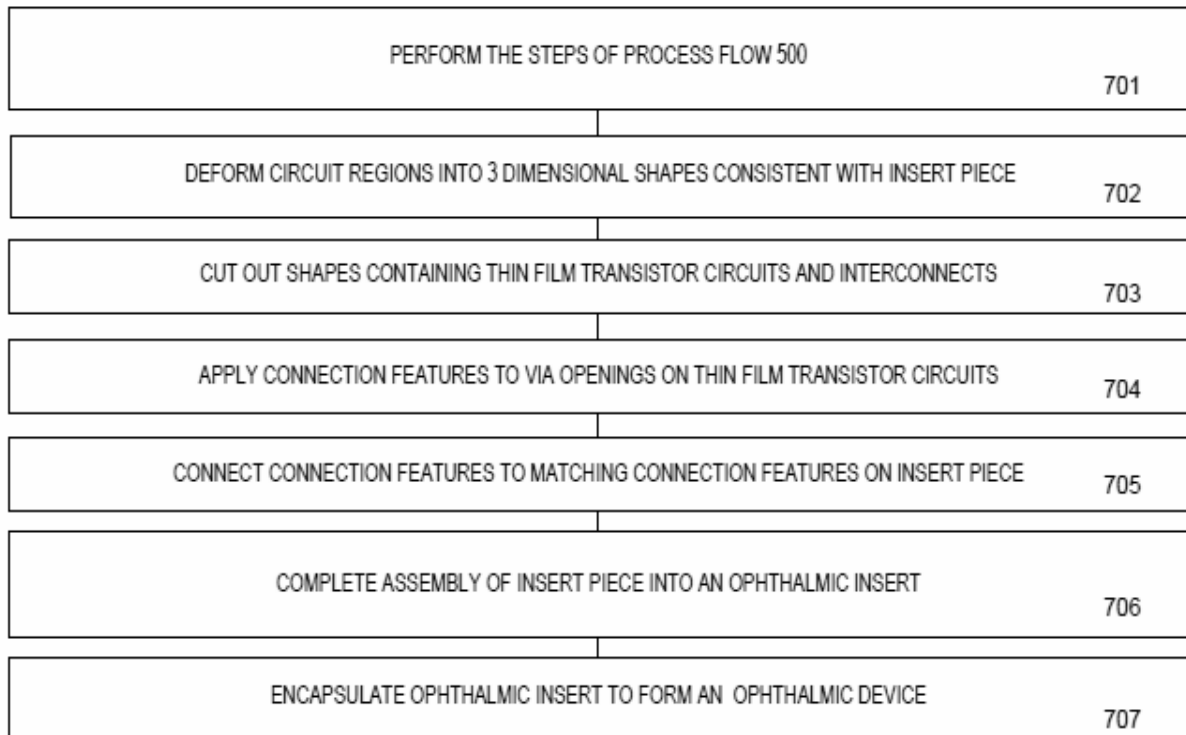
700

FIG. 7

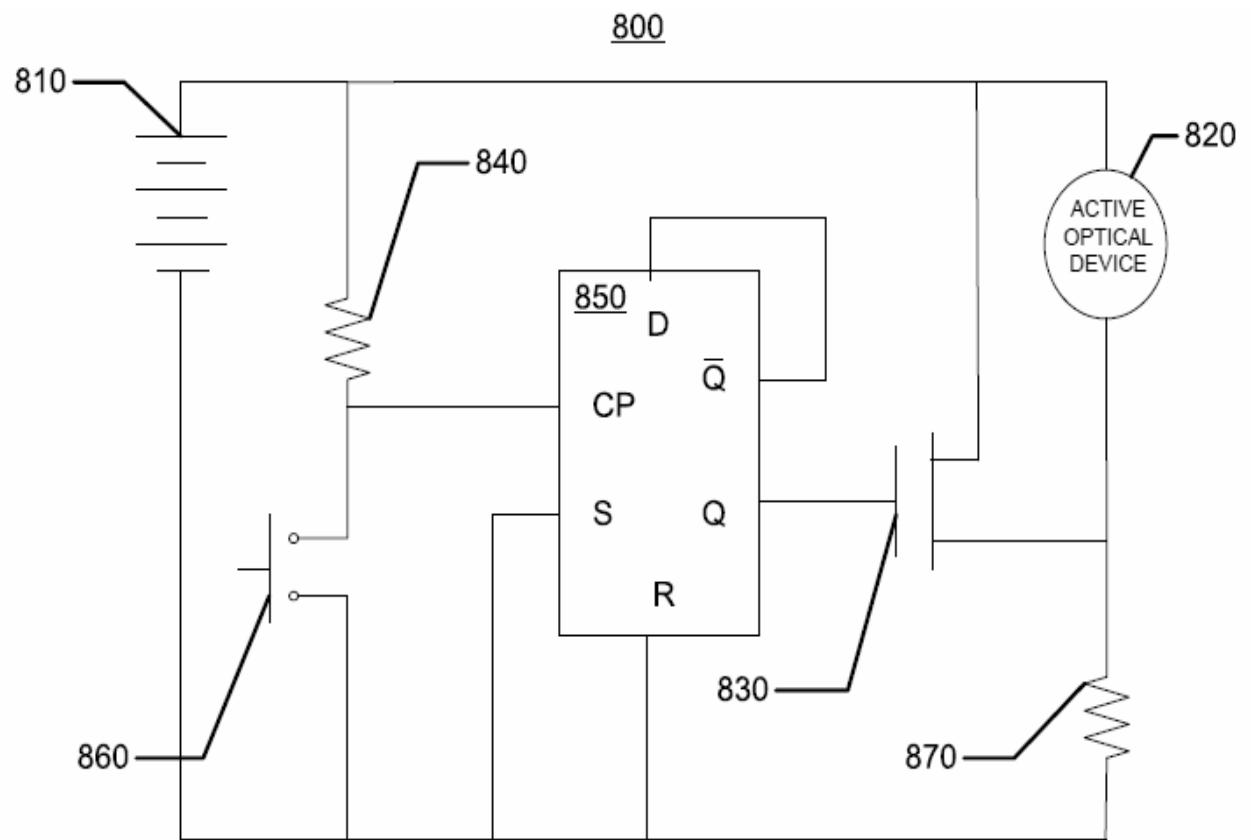


FIG. 8

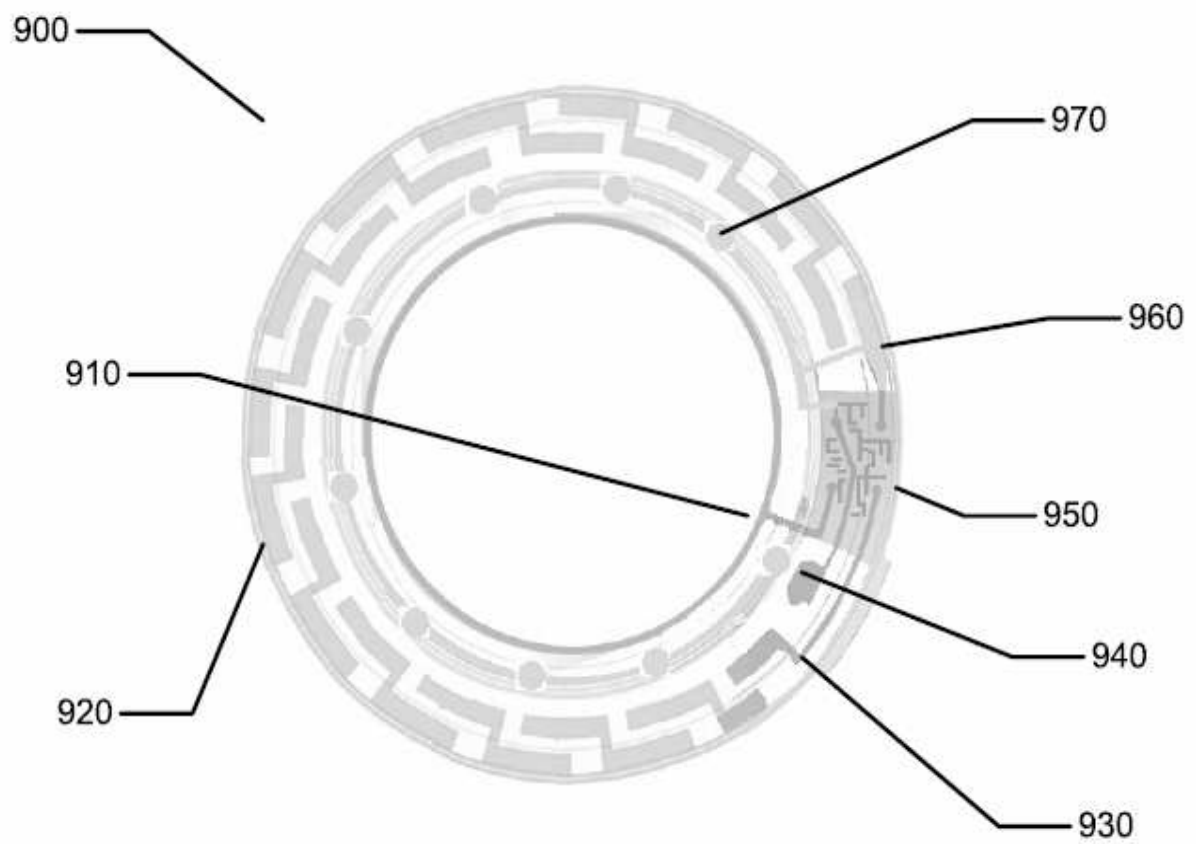


FIG. 9